



The Abdus Salam
International Centre for Theoretical Physics


United Nations
Educational, Scientific
and Cultural Organization


International Atomic
Energy Agency



SMR.1670 - 21

INTRODUCTION TO MICROFLUIDICS

8 - 26 August 2005

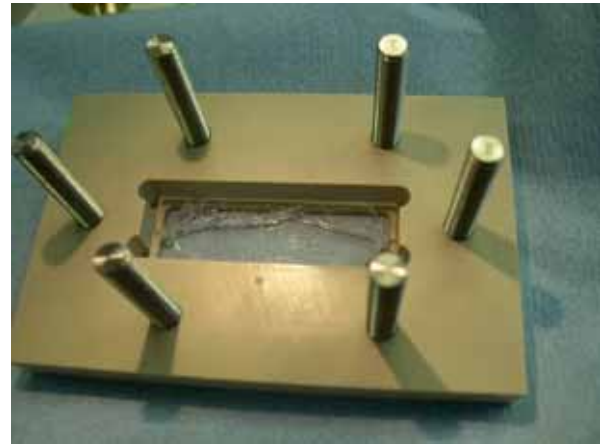
Reliability Issues

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Reliability issues

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MESA+ Institute for Nanotechnology
University of Twente

Summer School in Microfluidics
ICTP, Trieste, Italy



The fluids that go into the chip

- Gases and liquids: viscosity
- Liquids with particles: blood, soil samples, crystallites
- Liquids with gas: bubbles, liquid film in gas stream
- Two phase flows (oil and water; droplets, interfaces)
- Highly viscous liquids: glue, ink
- Corrosive solvents: tetrahydrofuran, alkaline, acid

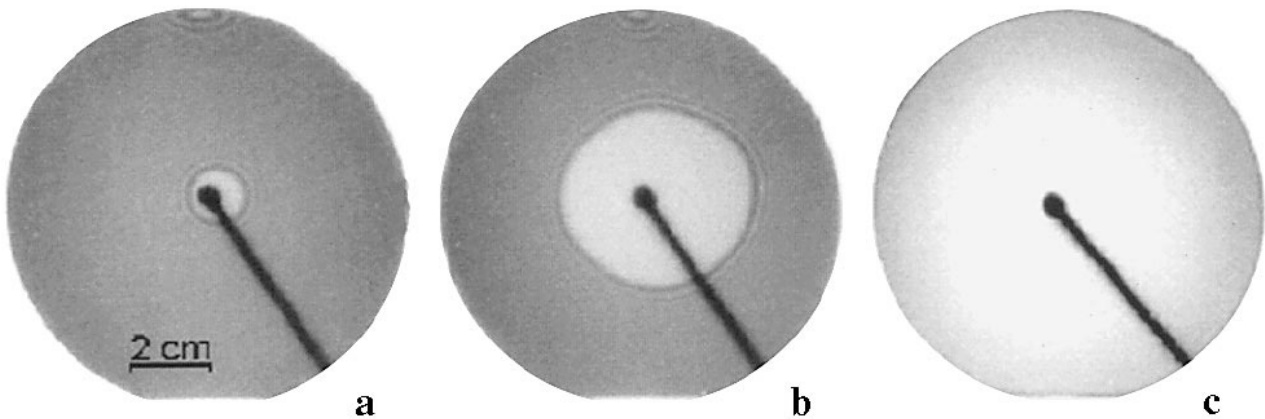
The conditions that may go on the chip

- Corrosive liquids
- High temperatures (microcombustor ~ 1000 °C)
- Low temperatures (microcooler for superconductors ~ 70K)
- High pressures (liquid chromatography 10~400 bar; microreactors ~ 10 kbar?)

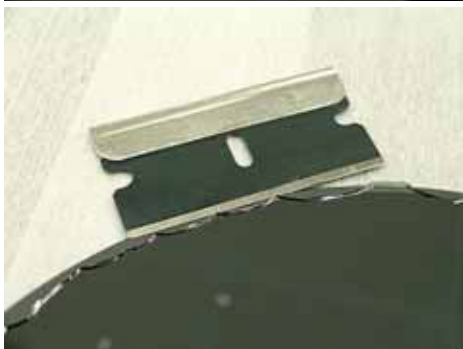


Wafer bond test methods

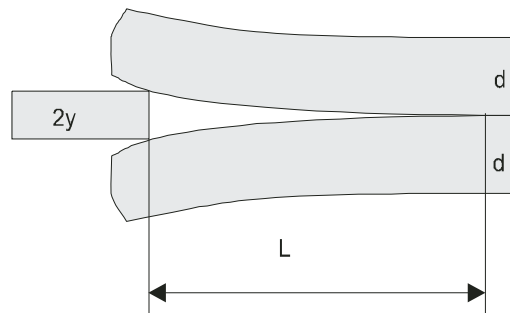
InfraRed microscopy: Newton rings



Blade insertion



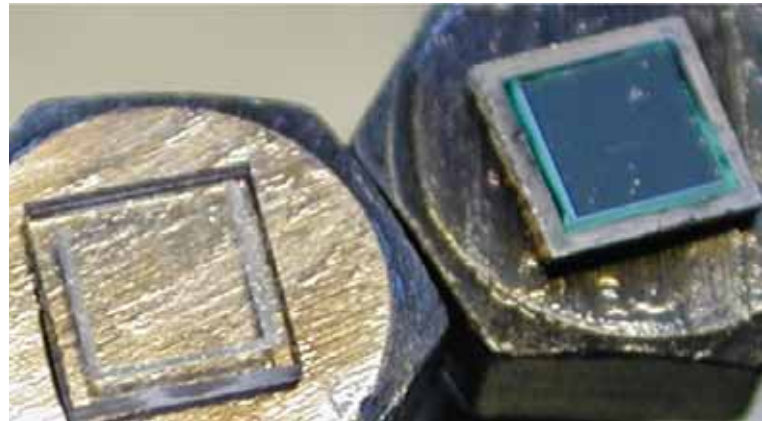
But if the bond is too good...



$$w_b = \frac{3Ed^3y^2}{8L^4}$$

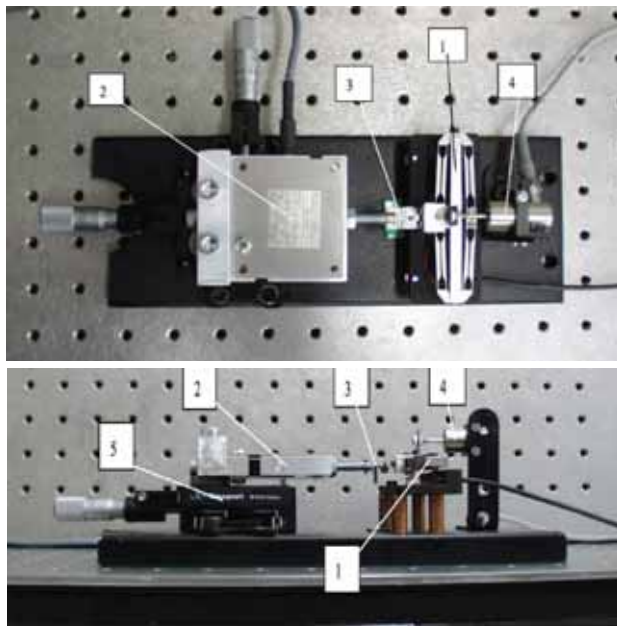
Crack opening by blade
or wedge insertion:
width of opening is
measure for effective
bonding energy

Pulling test - etched specimens (mesa)

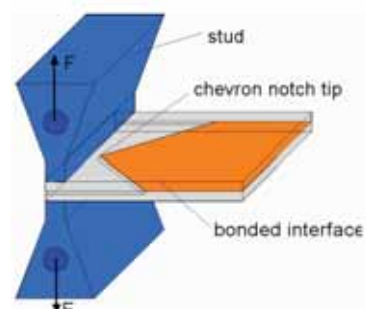
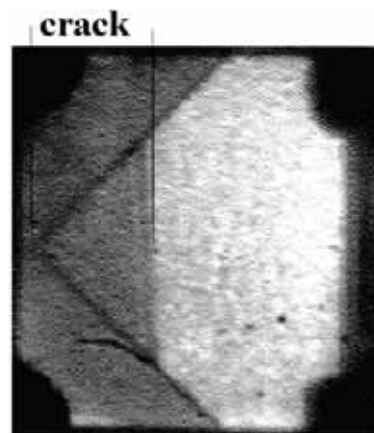


After the test

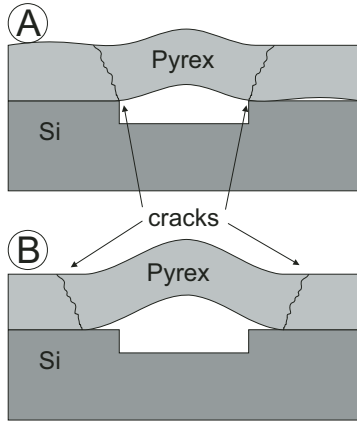
Pulling test - etched specimens (chevron)



1. piezoelectric actuator; 2. 10 N load cell;
3. sample; 4. displacement sensor; 5. sample stage

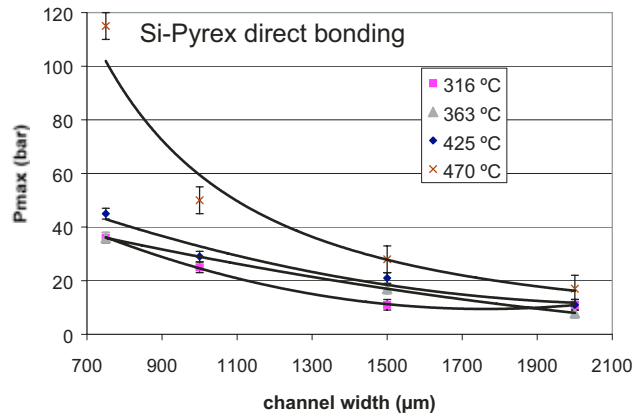
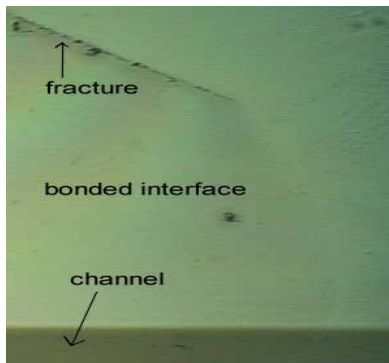


Hydraulic pressure on microchannel



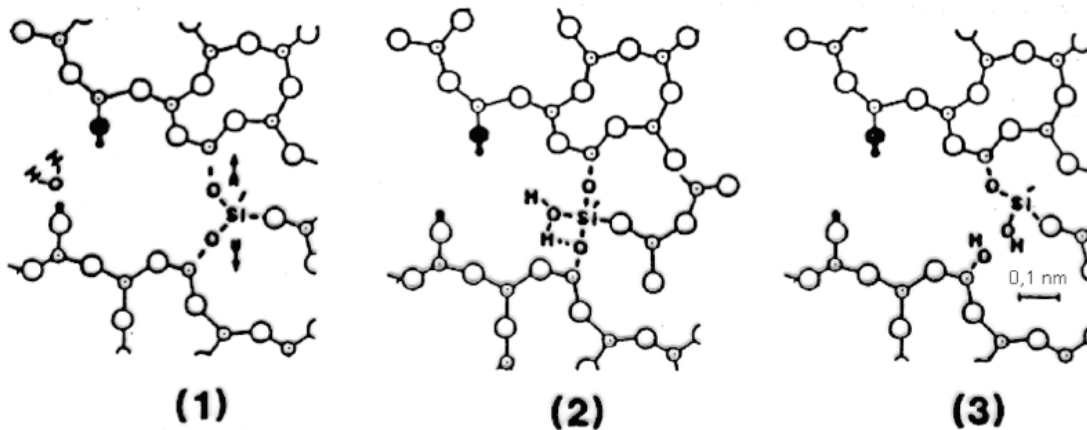
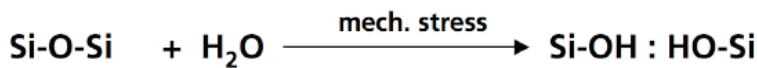
Pressure at which interface starts to open:

$$p = \sqrt{\frac{2048Et^3\Delta\gamma_b}{77}} \frac{1}{w^2}$$



Blom e.a. J. MEMS 10, 158-164 (2001)

Crack opening + stress corrosion



Hydraulic test equipment



MESA+

University of Twente
The Netherlands



Case study:

High pressure chemistry in a miniaturised system

The benefits of high pressure for chemistry

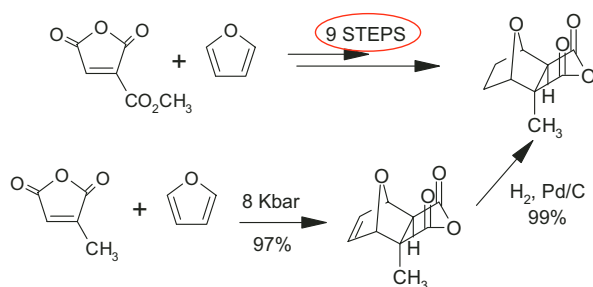
Molar activation volume: $(\partial \ln k / \partial p)_T = -\Delta V^\ddagger / RT$

E.g. if molar activation volume = -20 cm³/mol:

2870 atm → factor 10 increase in kinetic constant

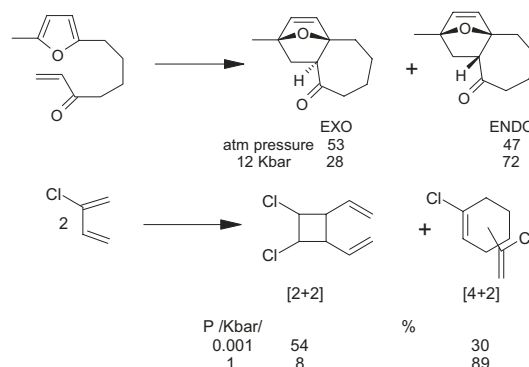
5740 atm → factor 100

Example: less reaction steps (→ higher yield)



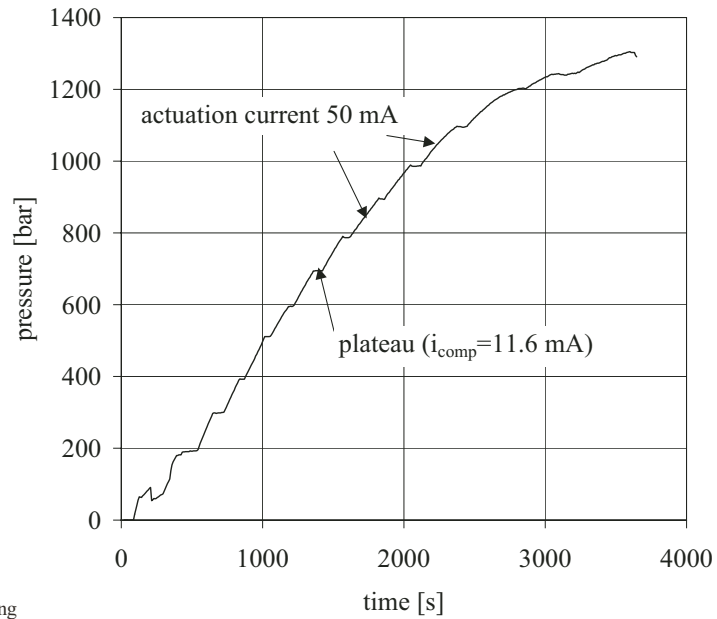
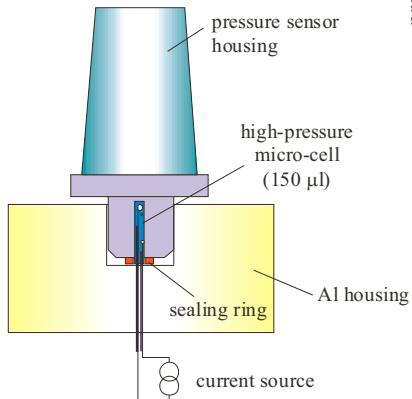
Grieco e.a. J. Am. Chem. Soc. 112, 4595-4596 (1990)

Example: higher selectivity



Jenner, Tetrahedron 53, 2669-2695 (1997)

Miniaturised pressure generator using electrolysis



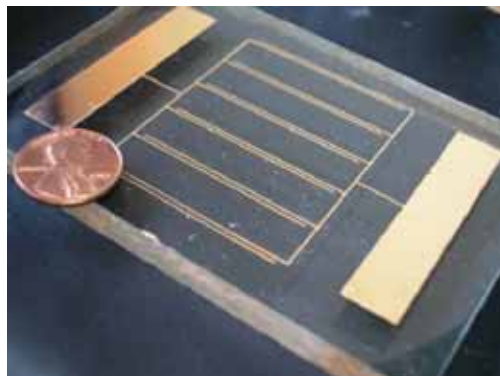
Electrolytic pressure generation

Drawbacks:

- slow (but miniaturisation and integration may help)
- separation of anode and cathode chambers is required

Advantages:

- reactive gases generated in-situ (Cl_2 , F_2 , D_2 , CO_2 , I_2 , Br_2 , etc.)
- local generation of gases



PMMA with gold pattern
-cracks at 200 bar

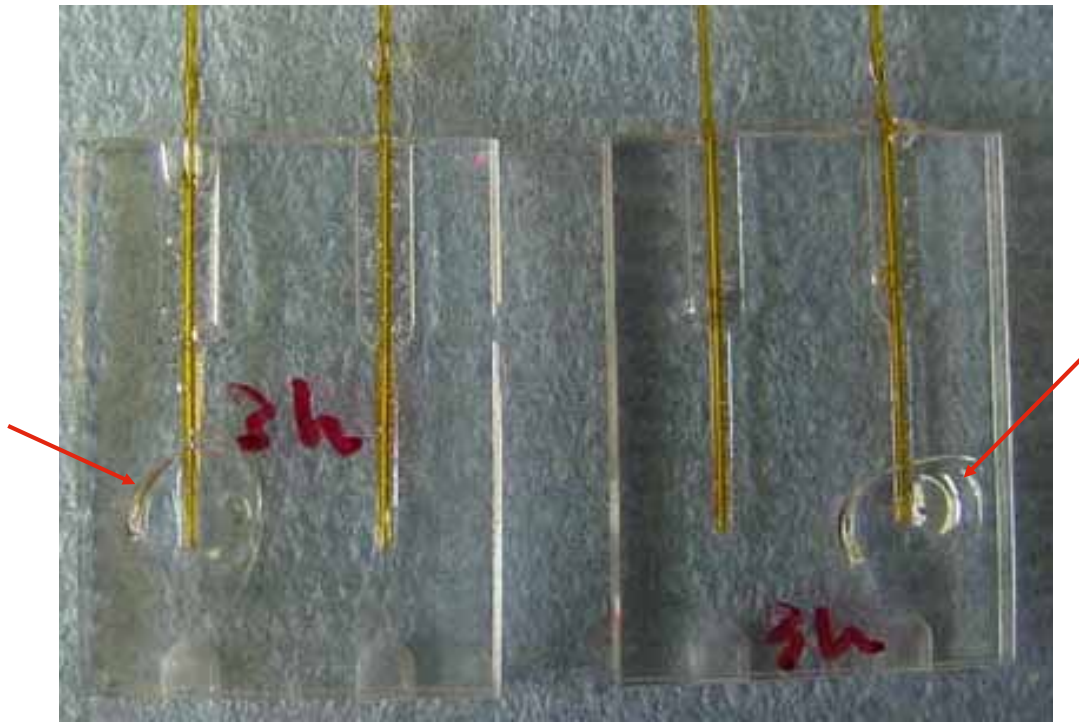


Pressure testing on glass chips

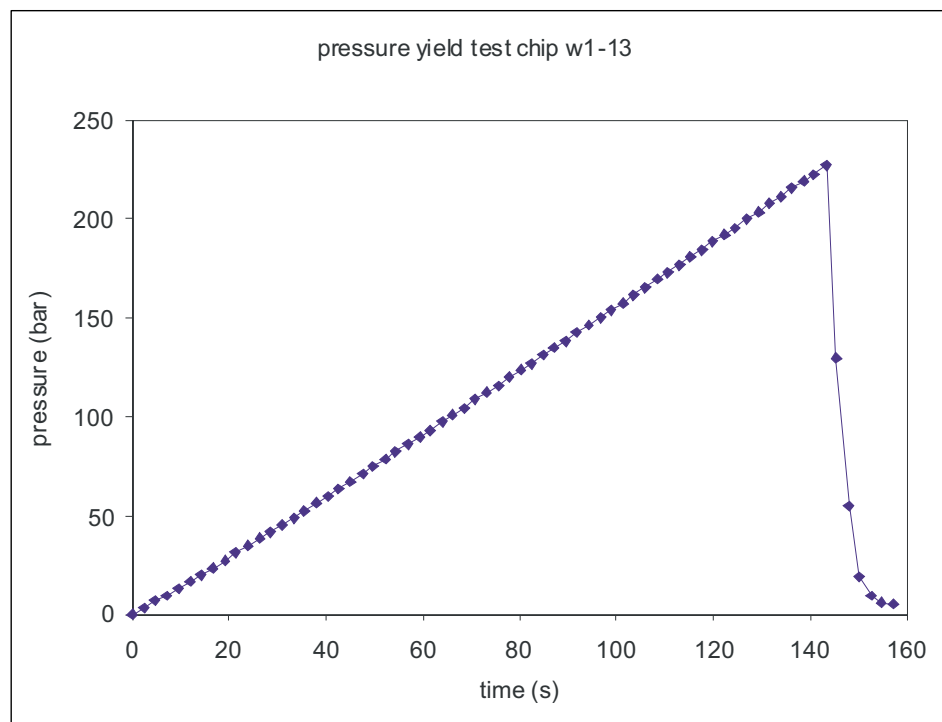
High-pressure (microreactor) setup



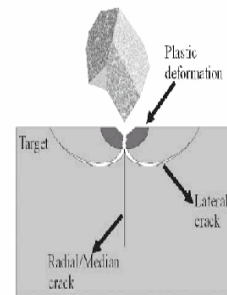
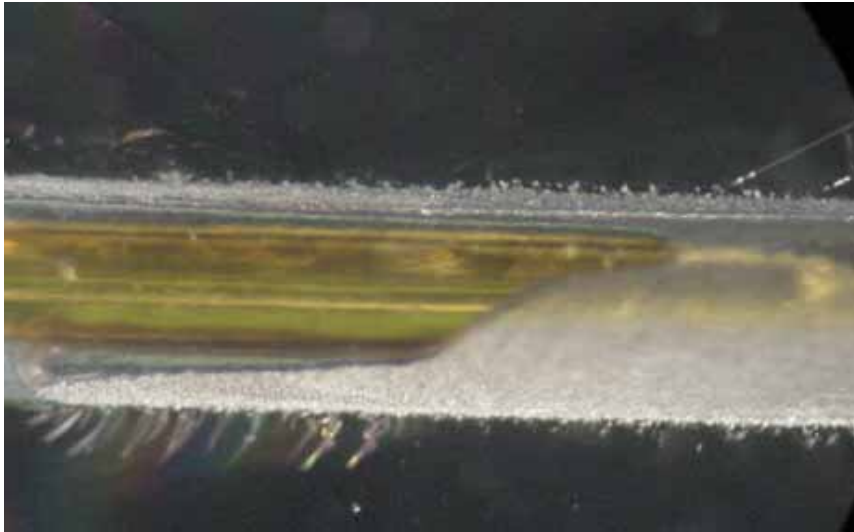
First high pressure tests on glass chips



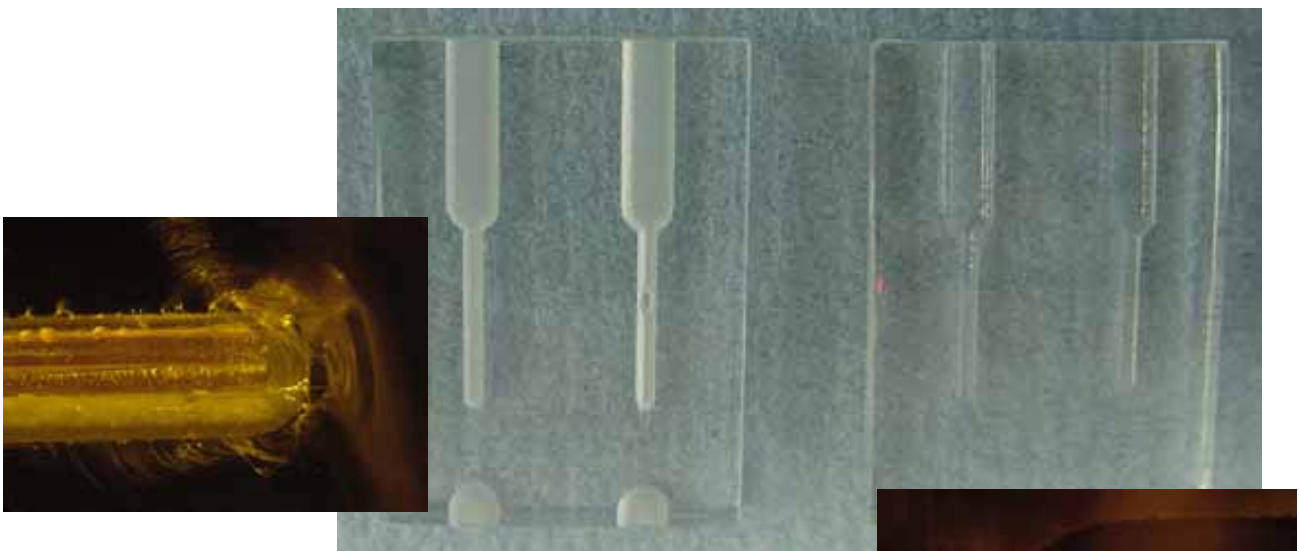
experimental yield strength \ll theoretical strength



Reasons for low yield strength: micro cracks due to fabrication method (powder blasting)



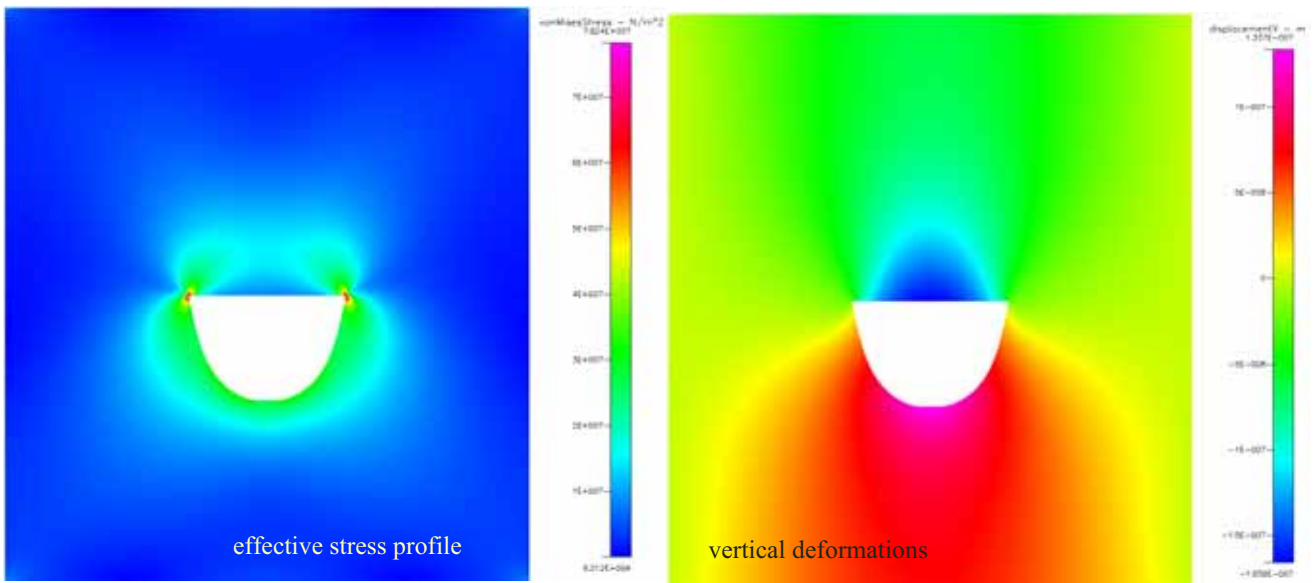
Annealing reduces roughness/cracks



Before and after annealing for 3 hours at 730°C

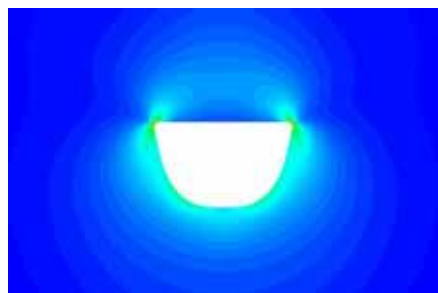
Yield strength rises from 70-120 atm to 250-290 atm

Stress concentration due to etching profile

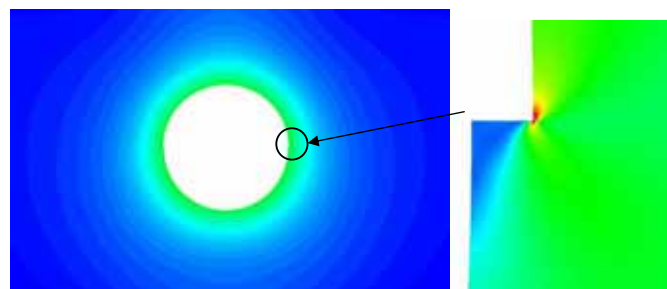


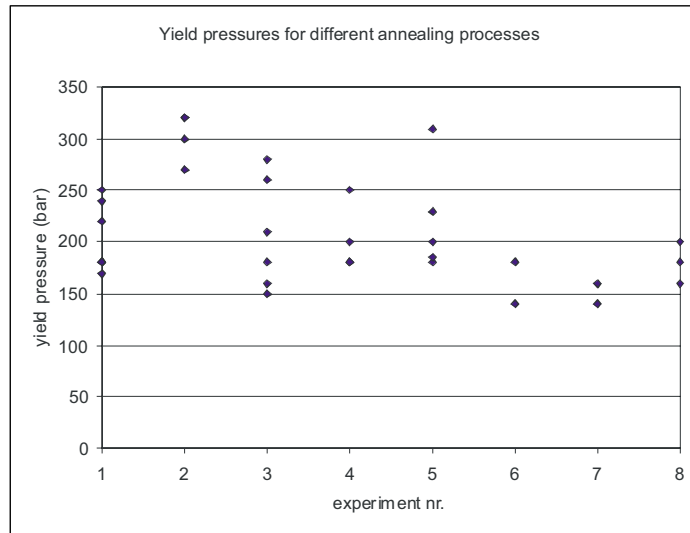
Stress profiles

- Standard channel:
stress concentration at
the edge



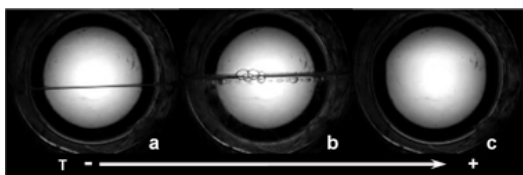
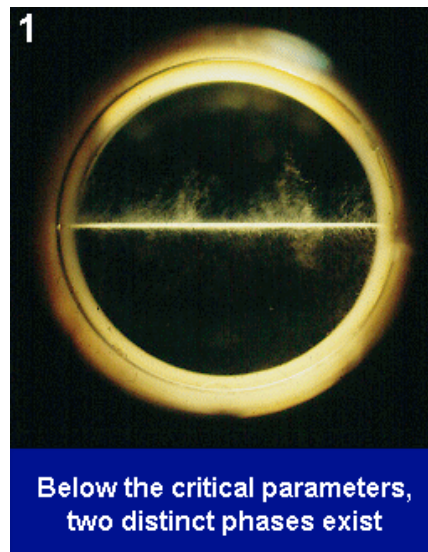
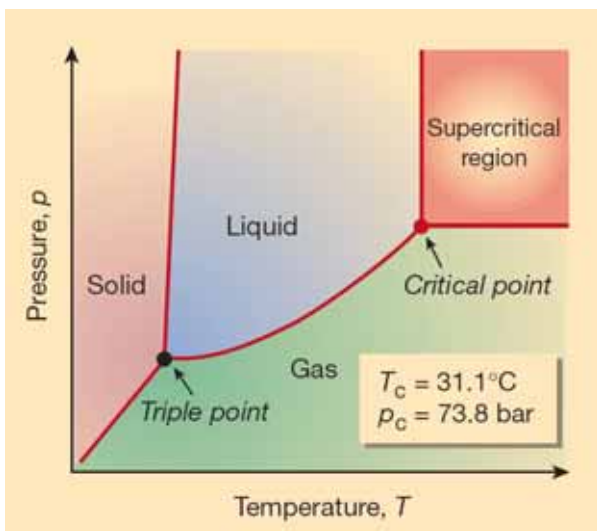
- Perfect circular channel:
ideal but not feasible



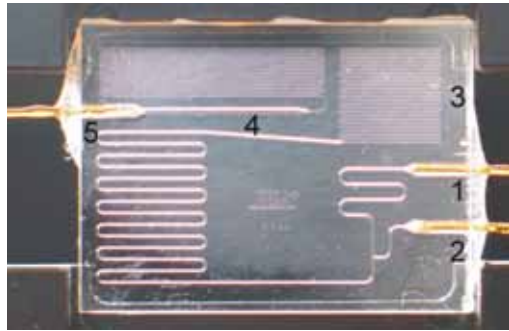
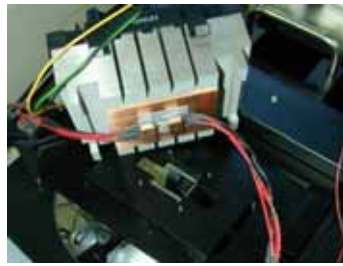
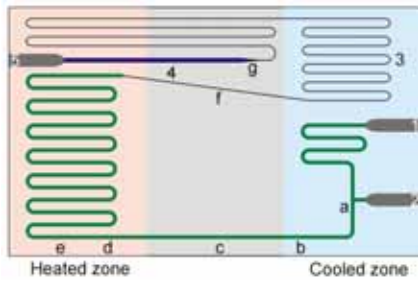


- | | |
|-------------------------------------|---|
| 1) Standard annealing: 6 hrs 600 °C | 5) 1:30 hrs 700 °C + 10 hrs 680 °C |
| 2) 6 hrs 680 °C | 6) 3 hrs 680 °C channel down during annealing |
| 3) 6 hrs 700 °C 4) 10 hrs 680 °C | 7) 3 hrs 680 °C channel up during annealing |
| 4) 10 hrs 680 °C | 8) 6 hrs 680 °C second batch |

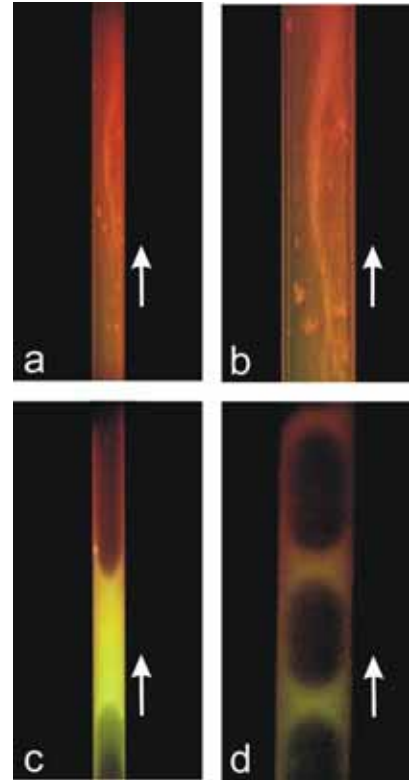
Current work: SC-CO₂



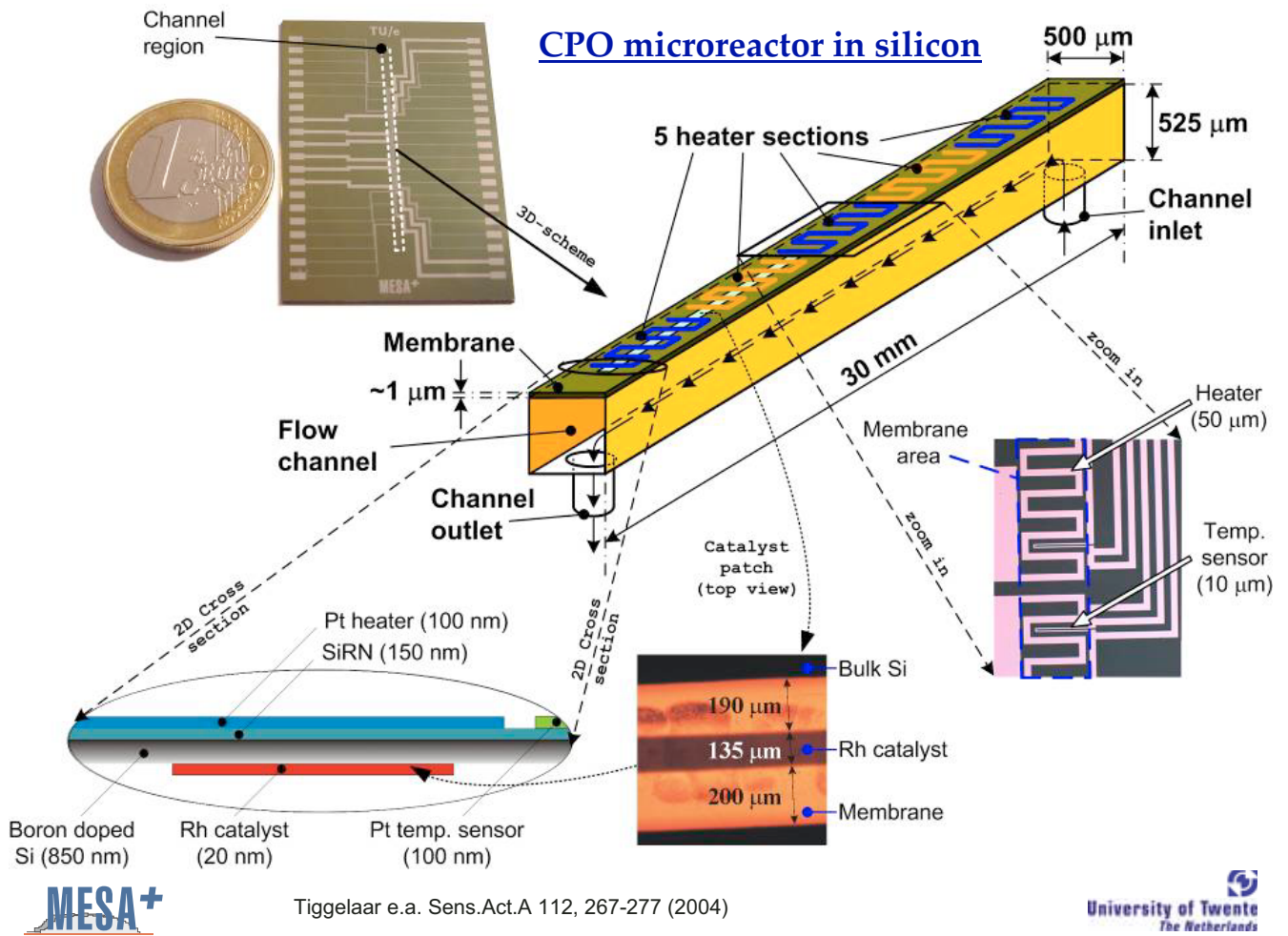
Visualisation critical transition



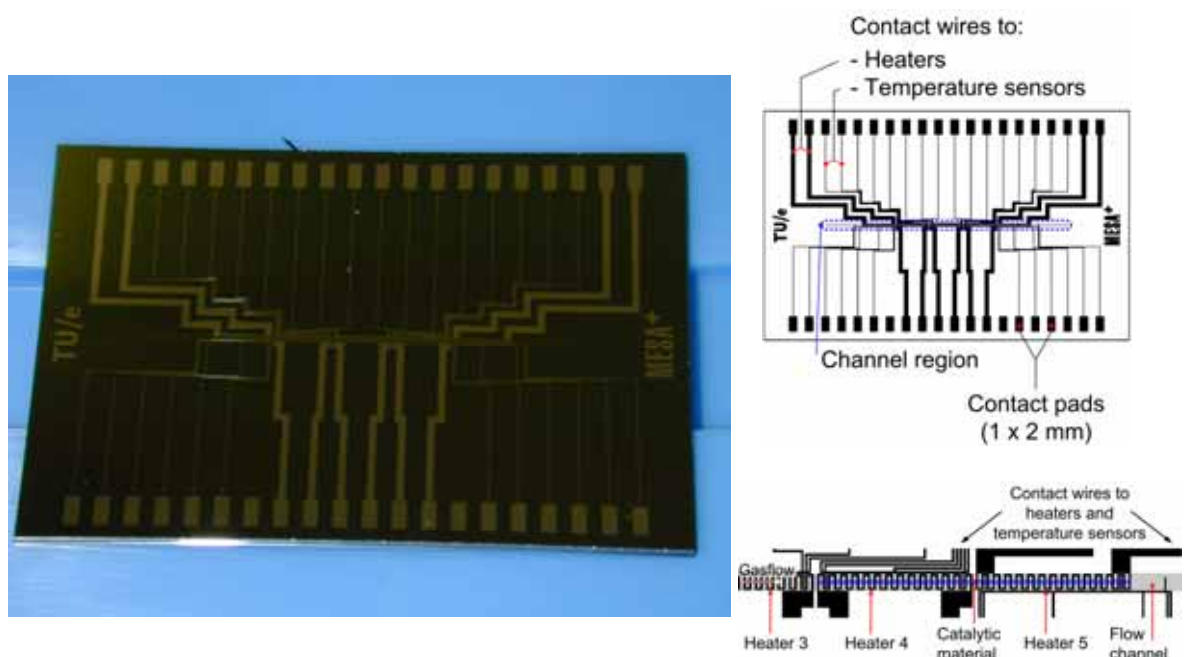
Flow patterns
below (c,d)
above (a,b)
critical point



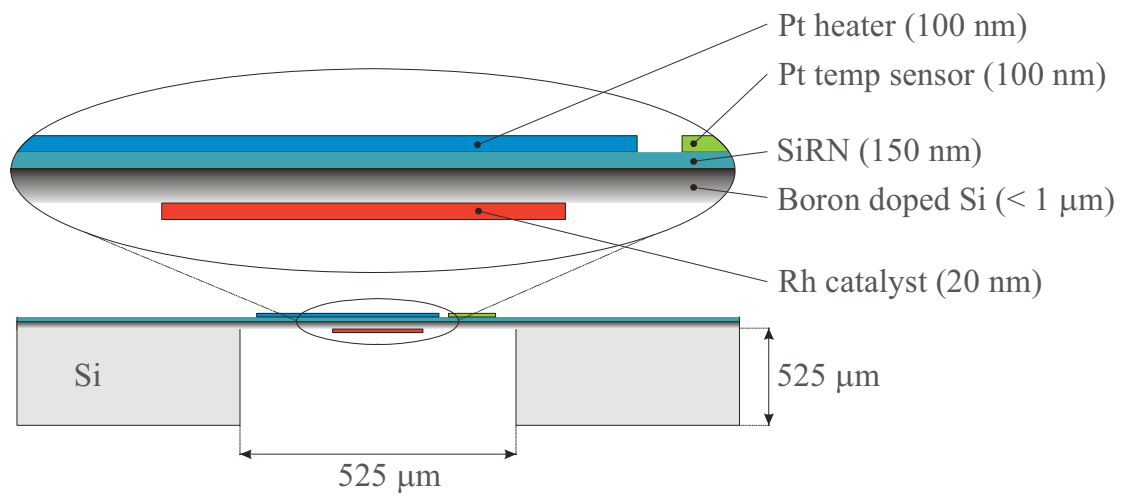
High-temperature microreactors for catalytic partial oxidation studies



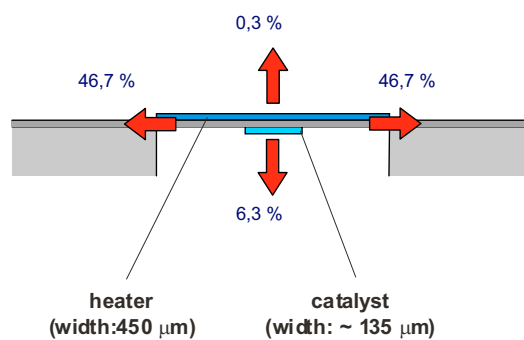
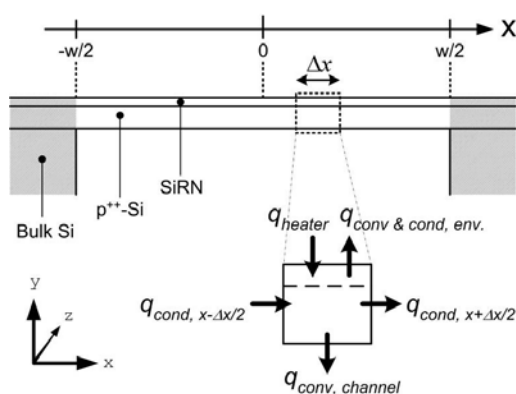
CPO microreactor in silicon



Cross-section of membrane

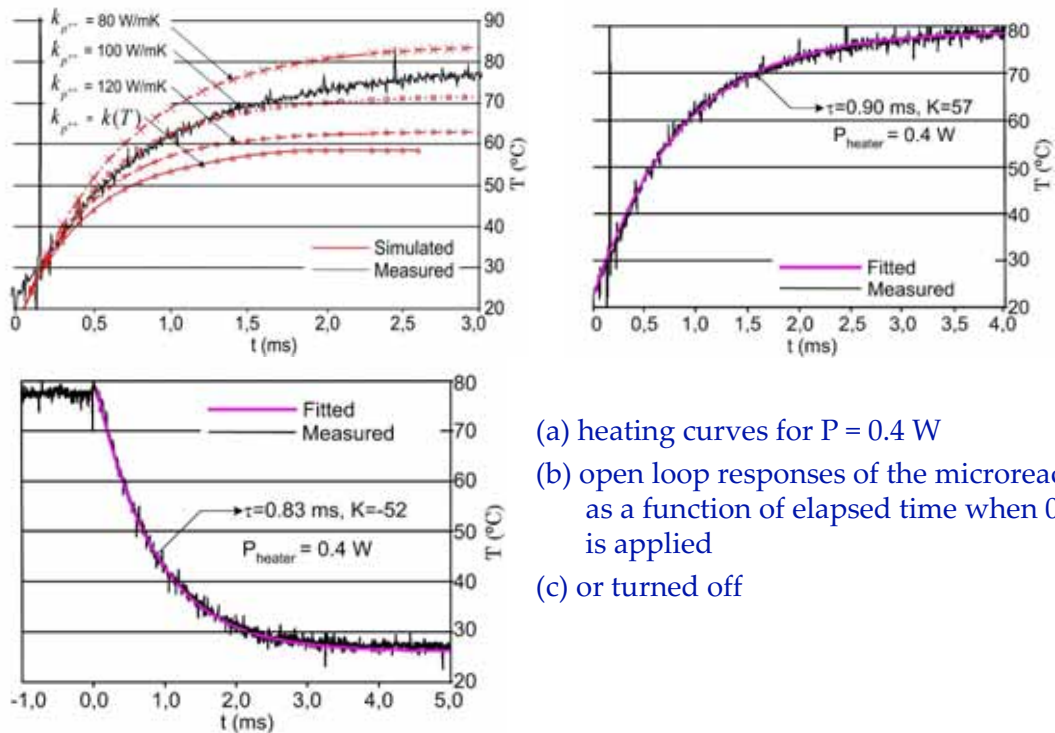


Thermal modelling

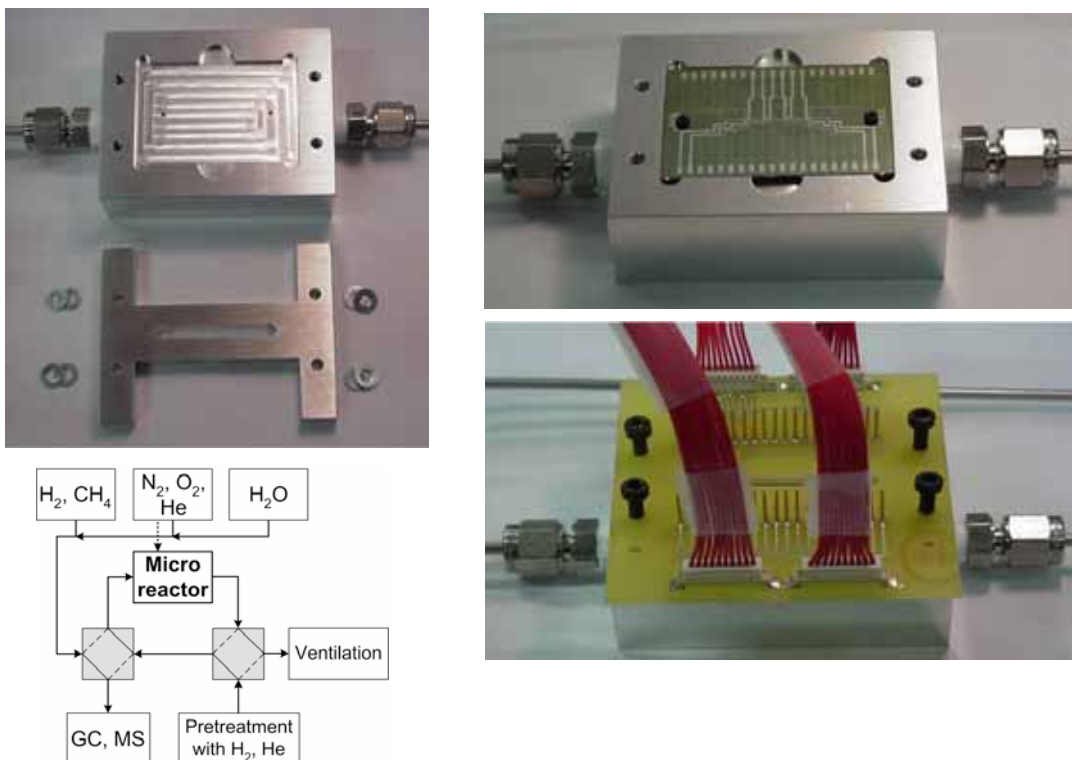


calculated heat losses in the membrane (150 nm SiRN and 850 nm p^{++} -Si)

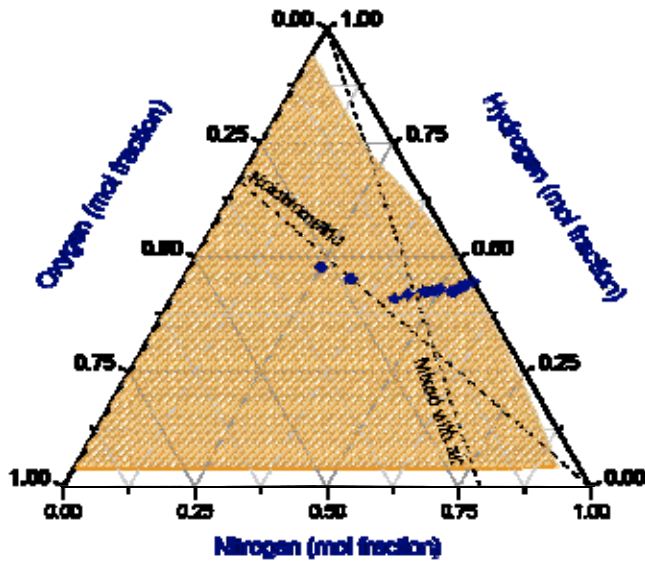
Transient effects



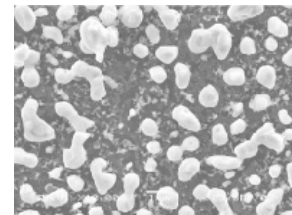
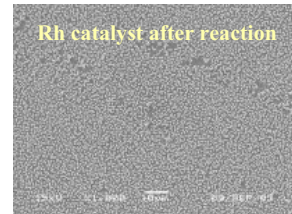
Microreactor testing set-up



Safe hydrogen oxidation



Ignition at 280°C
Temp. rises to 400°C
100% O₂ conversion



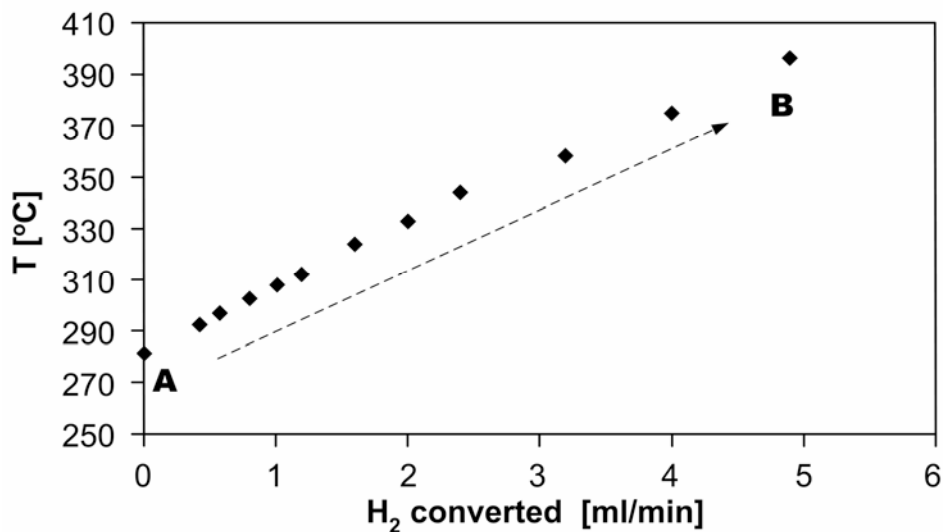
PhD work of Roald Tiggelaar (UT) and Poul van Male (TUE, Schouten) 2000-2004



R.M. Tiggelaar, PhD Thesis University of Twente, 2004



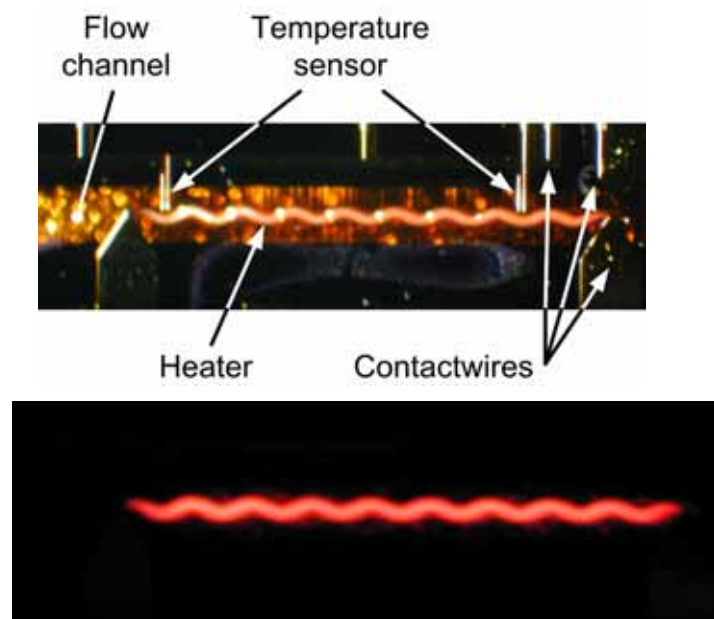
Hydrogen conversion



R.M. Tiggelaar, PhD Thesis University of Twente, 2004



Visible glow from heaters on membrane



Estimated temperature > 725 °C

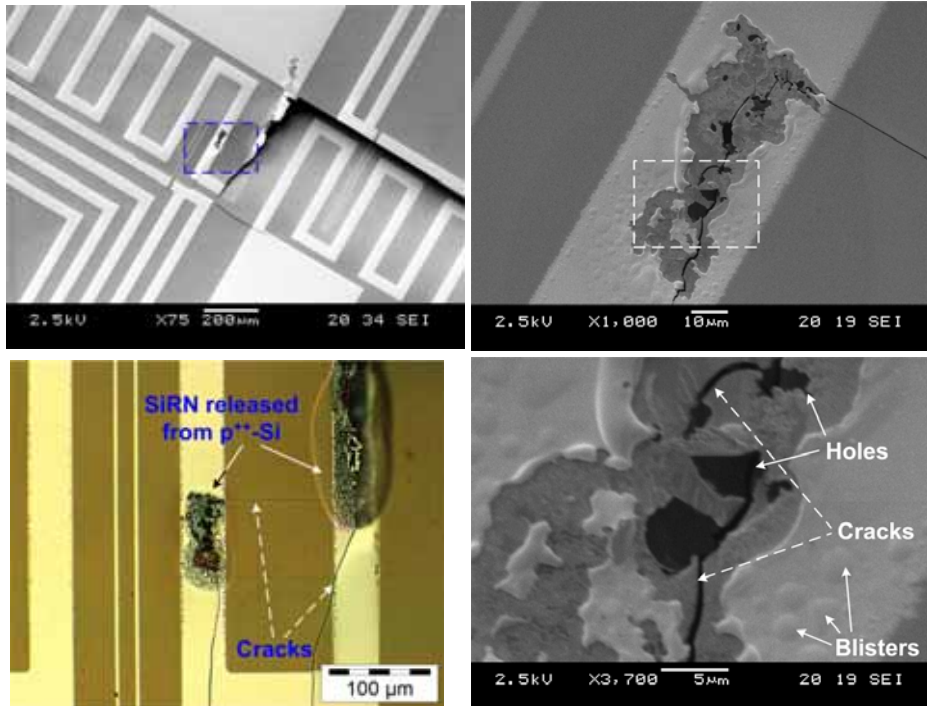


R.M. Tiggelaar, PhD Thesis University of Twente, 2004

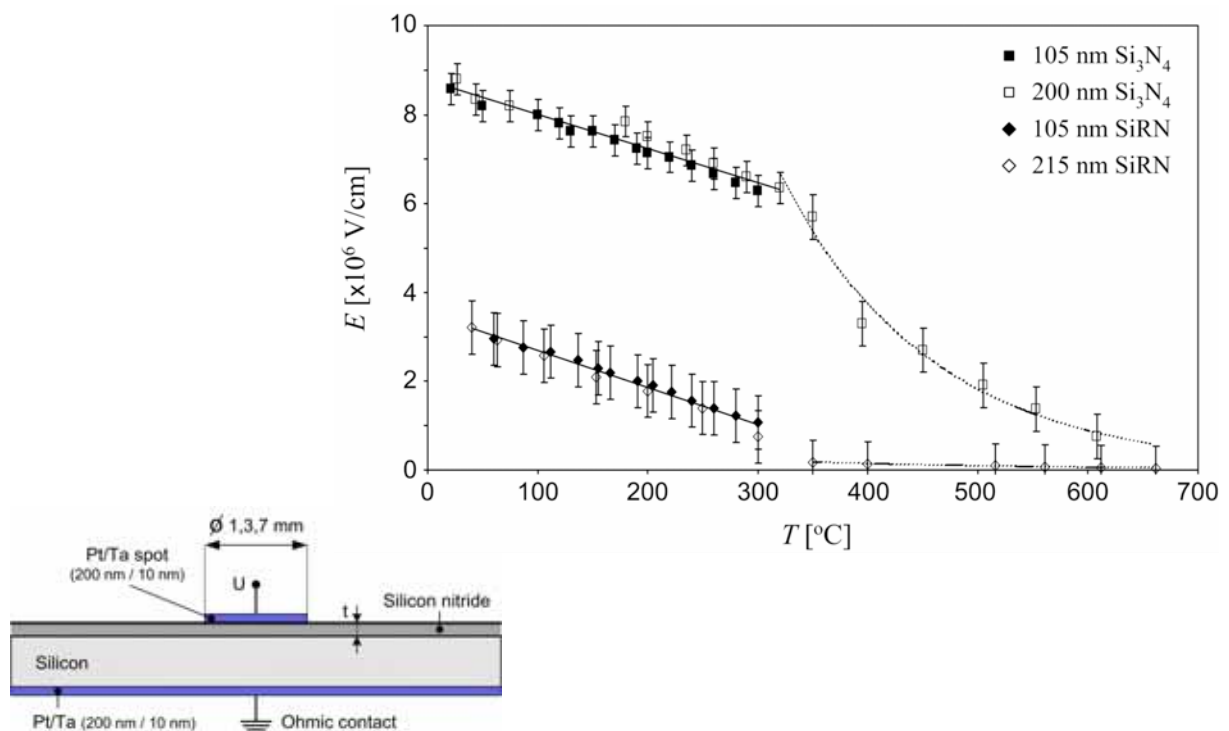


Materials aspects of high-temperature microreactors

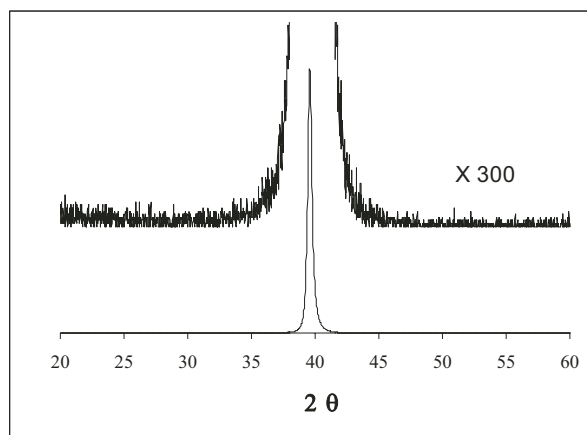
Breakdown of microreactors



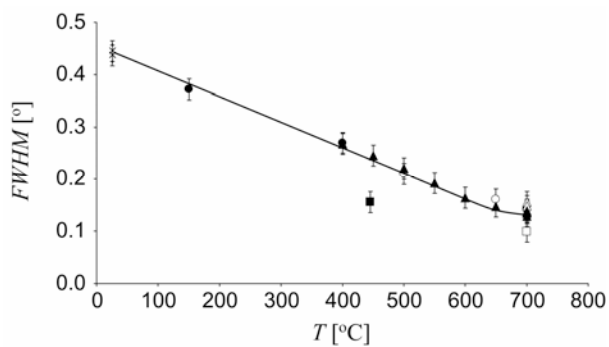
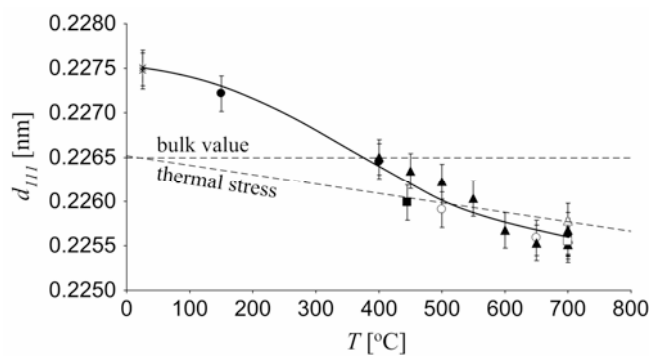
Breakdown of silicon nitride



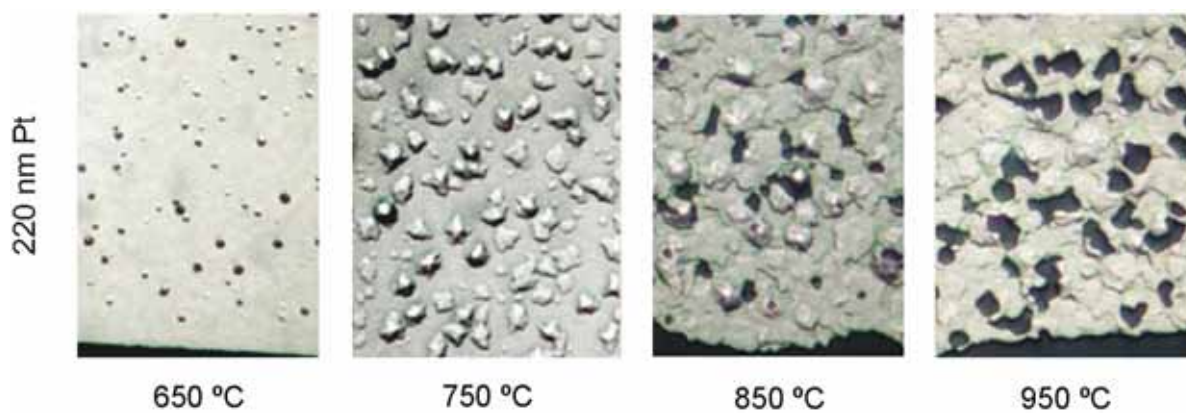
Pt at high temperatures



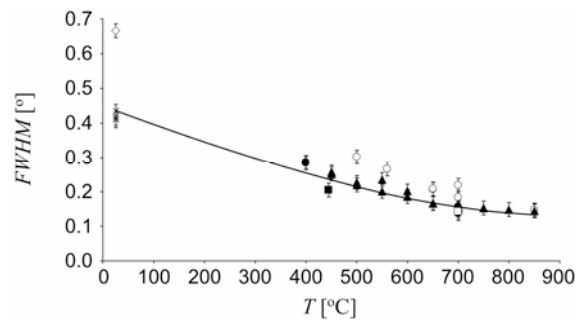
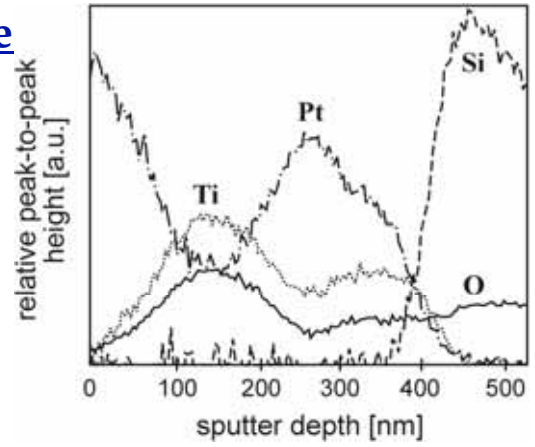
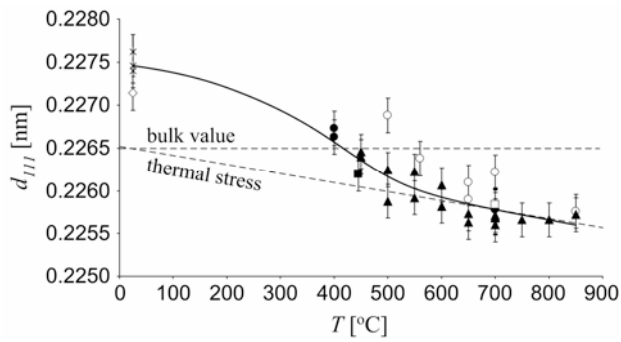
X-ray diffraction of Pt film



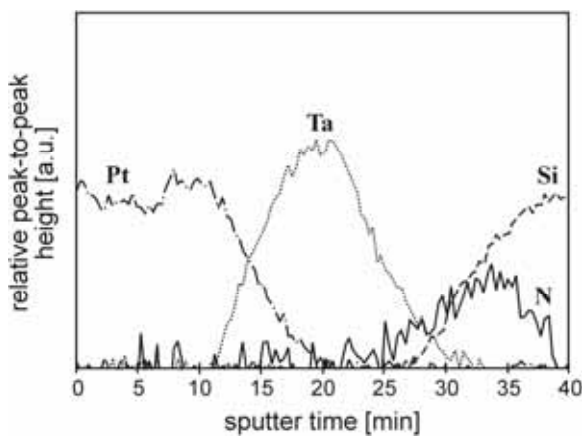
Pt at high temperatures (in air)



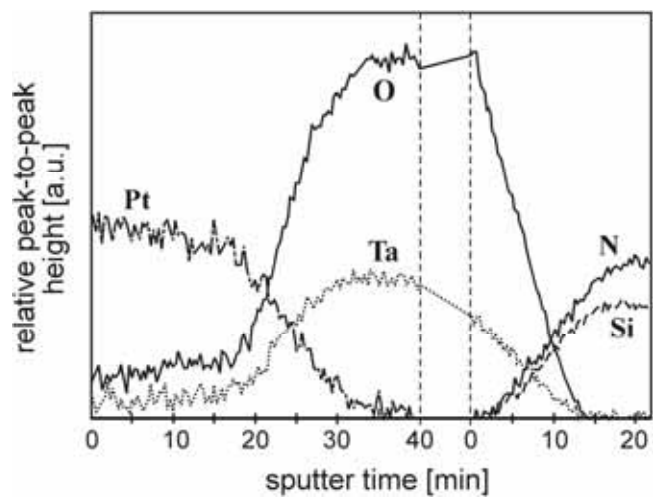
Pt-Ti at high temperature



Pt-Ta at high temperatures

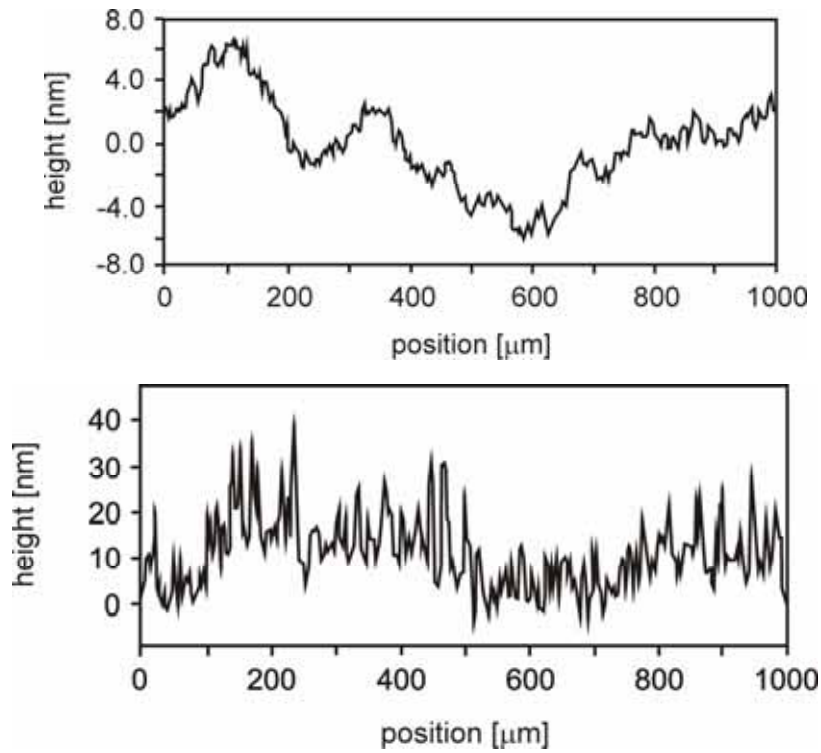


before annealing

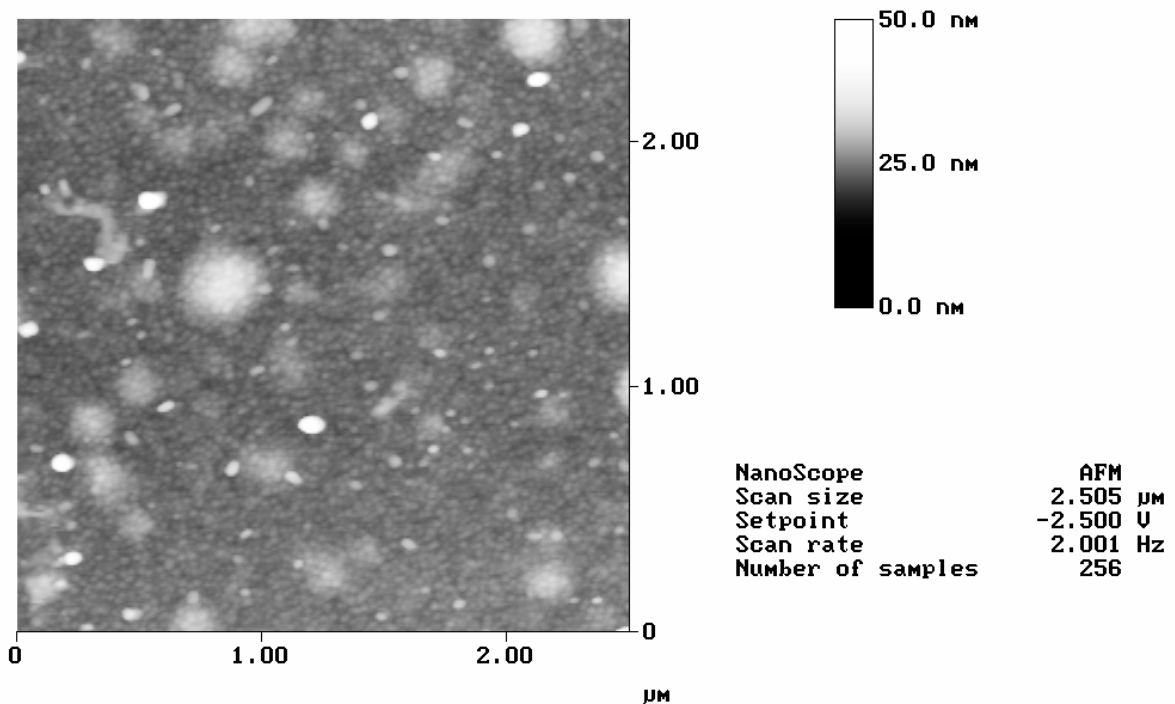


after annealing at 700 °C

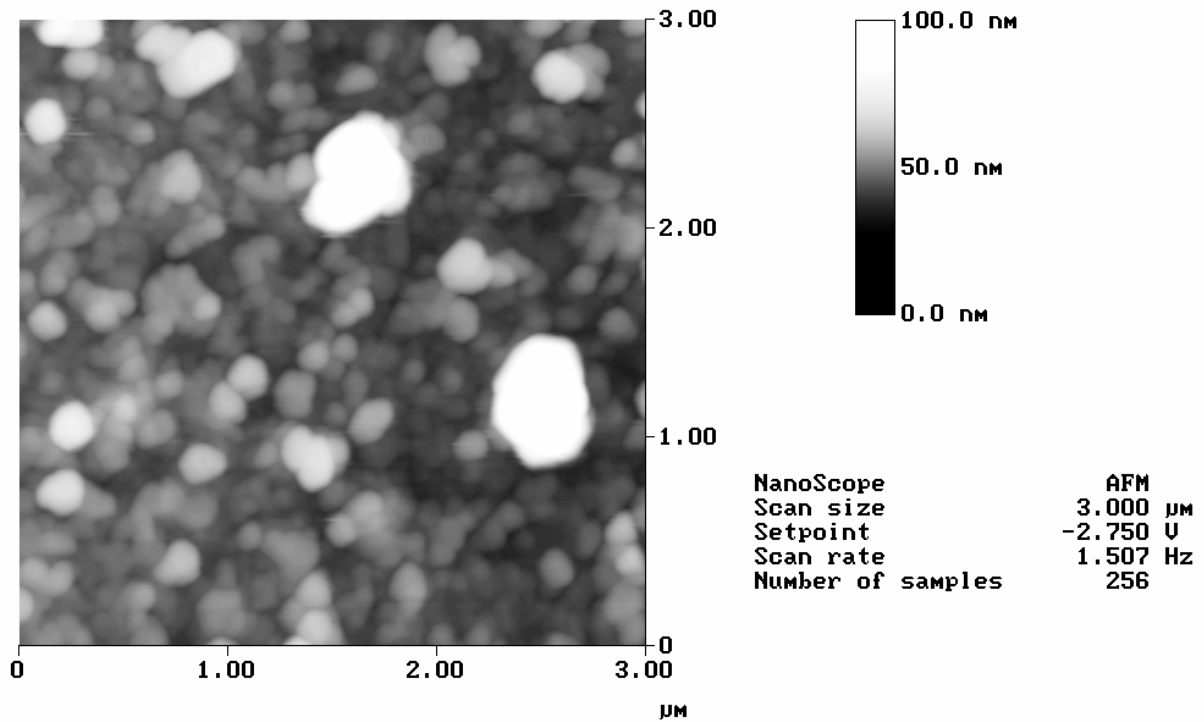
Pt-Ta roughness before/after annealing at 700 °C



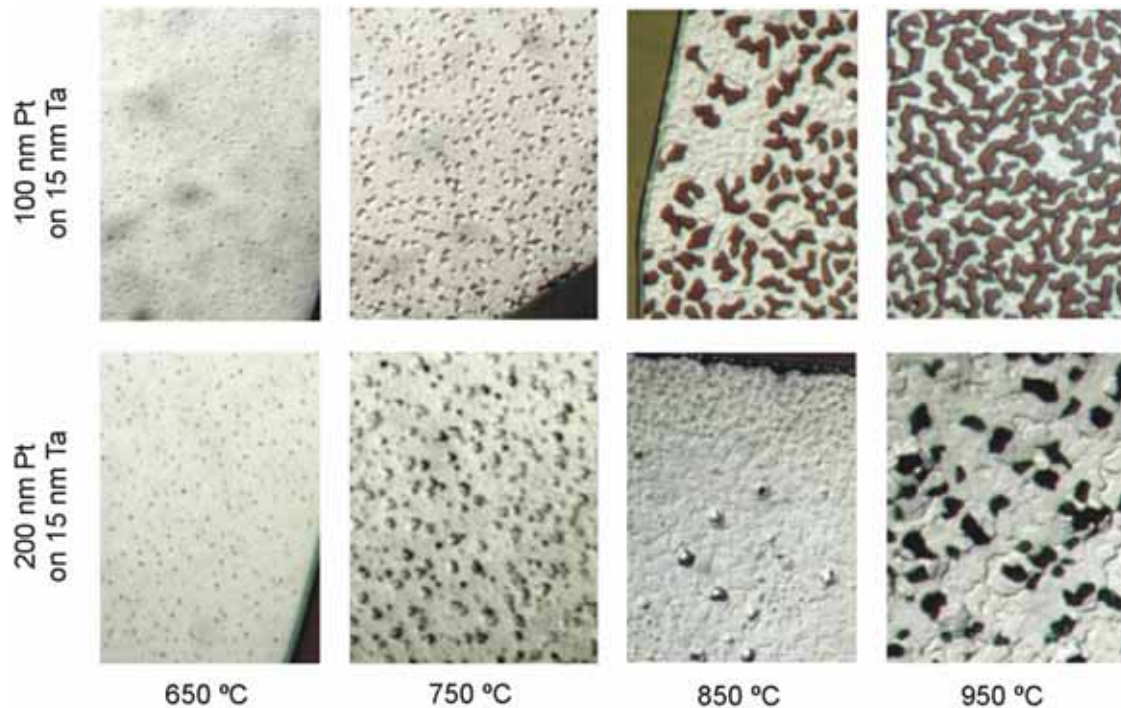
Pt-Ta before annealing -AFM image



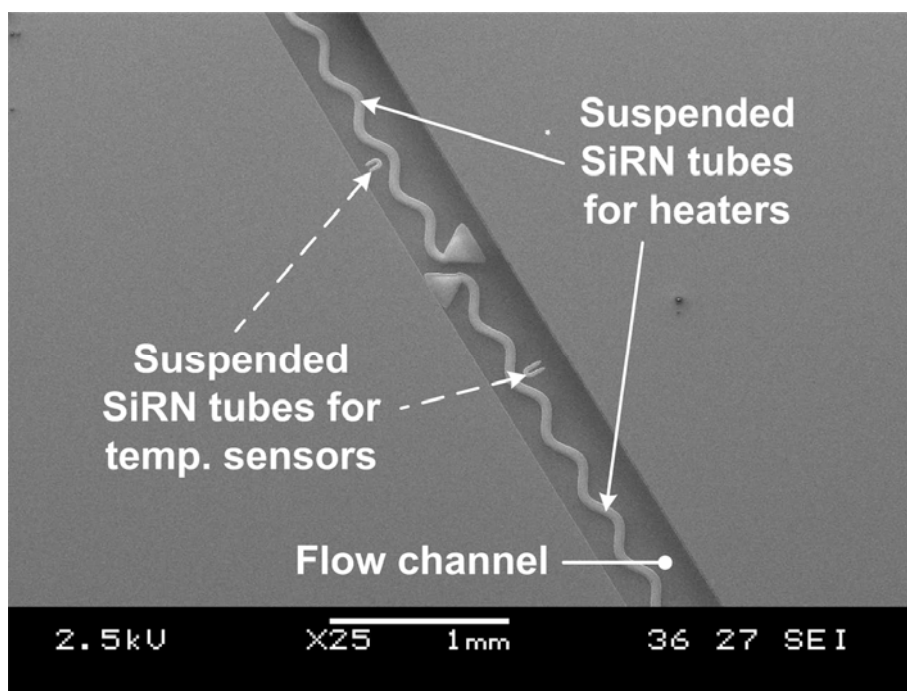
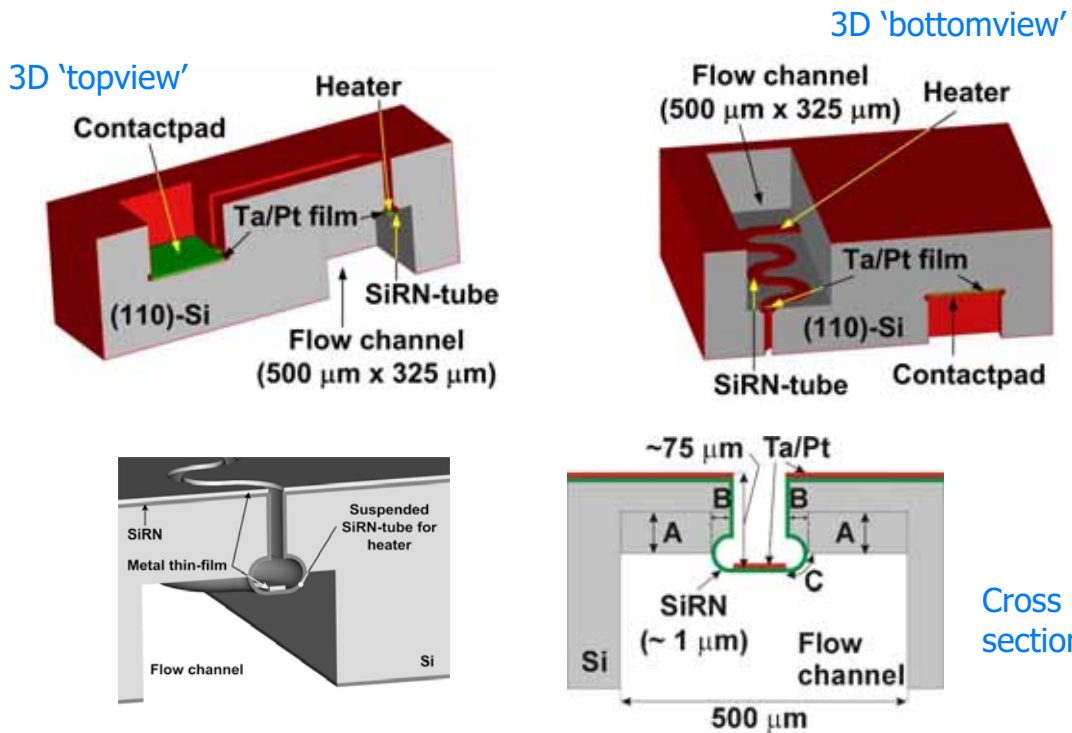
Pt-Ta after annealing at 700 °C - AFM image



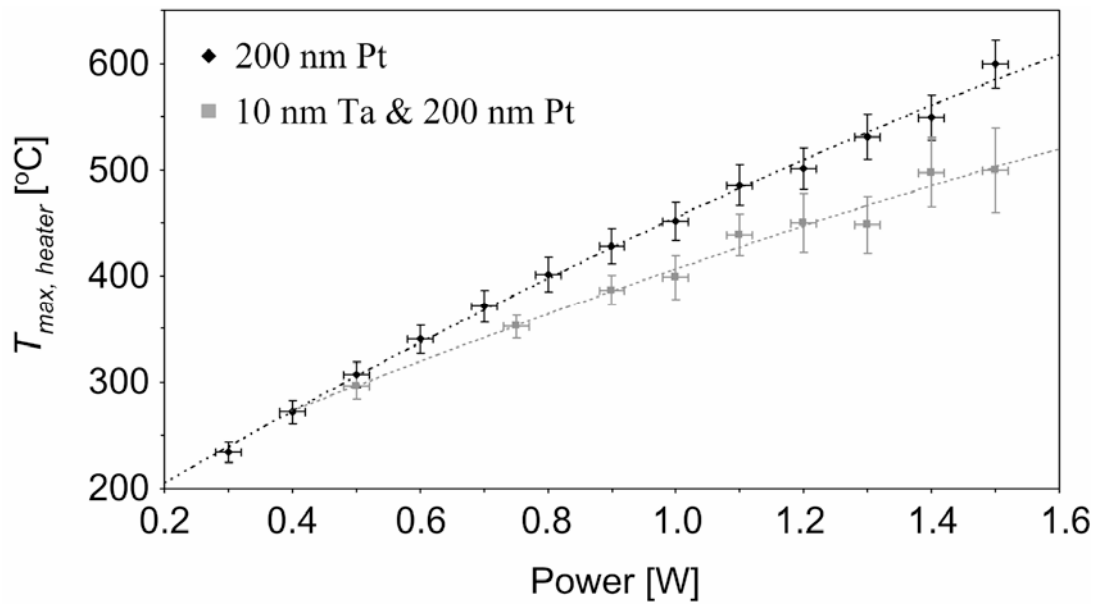
Pt-Ta at high temperatures



Re-designed microreactors



Measured temperatures on re-designed reactor



Breakdown of re-designed microreactors

